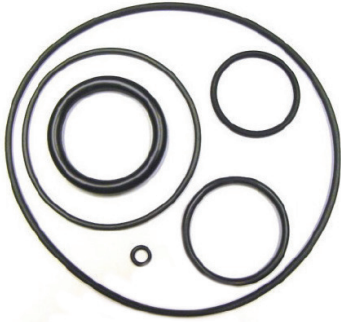




Kyflon™ 5400

Perfluoroelastomer Semiconductor Grade O-Rings and Seals

Kyflon™ 5400 Data Sheet



- **Low Particulation**
- **Outstanding Plasma Resistance**
- **Handles Temperature Excursions to 300° C**

Kyflon 5400 has been formulated to perform in aggressive dry plasma systems. It provides enhanced plasma resistance and minimal particulation that allows for higher wafer yields. It is recommended for both static and dynamic oxide etch wafer processing applications. Kyflon 5400 can be used at service temperatures up to 280° C with excursions to 300° C.

Applications include: Bell Jar Seals, Chamber Lid Seals, Door Seals, End Point Windows, Gas Inlet Seals, Isolator Valve Seals, KF-Fittings and Window Seals

Typical Properties

Physical Properties	ASTM Method	Typical Value
Color		Purple
Hardness, Shore A. Points	D2240	85
Temperature Retraction TR-10 °C	D1429	-5°C
Elongation @ Break %	D1414	150
Tensile Strength @ Break, psi	D1414	2200
Service Temperature Range, °F		-5° F to 590° F
Service Temperature Range, °C		-20° C to 310° C
Specific Gravity		2.04
Compression Set @ 25% Deflection 70 Hours @ 405°F/207°C, in Air, % of original deflection	D395-03 Method B	28

Unless otherwise noted all tests conducted on AS 568 (-214) o-rings

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Statements and recommendations in this publication are based on our experience and knowledge of typical applications of this product and shall not constitute a guarantee of performance nor modify or alter our standard warranty for this product.

Prior to actual use it is highly recommended that suitable tests be run to determine this product's suitability in a specific application. This is critical where failure could result in injury or damage.